

## FEATURES

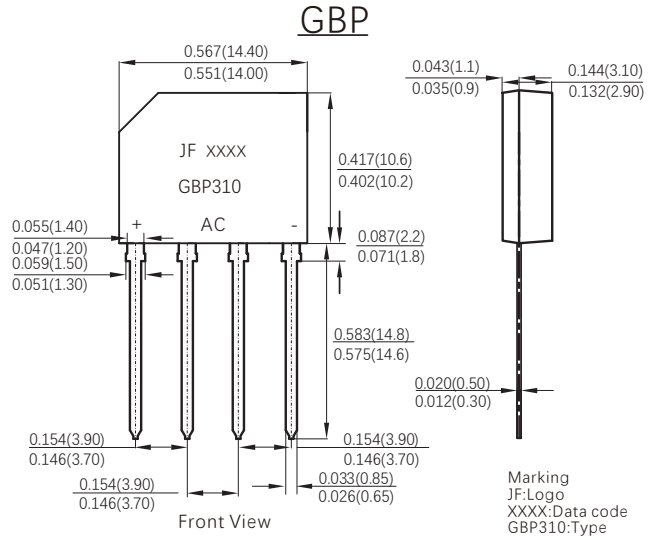
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated chip junction
- High current capability
- Low forward voltage drop
- High temperature soldering guaranteed:260°C/10 seconds at terminals
- Component in accordance to RoHS 2015/863/EU

## MECHANICAL DATA

- Case: GBP molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750,method 2026
- Mounting Position: Any

## TYPICAL APPLICATIONS

Used in AC/DC bridge full wave rectification for SMPS, lighting ballaster, adapter, charger, home appliances, office equipment, and telecommunication applications.



Dimensions in inches and (millimeters)

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, resistive or inductive load. For capacitive load, derate current by 20%.)

Parameters	Symbol	GBP3005	GBP301	GBP302	GBP304	GBP306	GBP308	GBP310	Units
Maximum Reverse Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current	$I_{FAV}$	3.0							Amps
Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed on Rated Load	$I_{FSM}$	60							Amps
Rating for Fusing (t = 8.3ms)	$I^2t$	14.94							A <sup>2</sup> S
Maximum Instantaneous Forward Voltage at 1.5A DC	$V_F$	1.0							Volts
Maximum DC Reverse Current at rated DC blocking voltage	$T_J=25^\circ\text{C}$	5.0							$\mu\text{A}$
	$T_J=125^\circ\text{C}$	100							$\mu\text{A}$
Typical Thermal Resistance Junction And Ambient (Note 2)	$R_{\theta JA}$	45							$^\circ\text{C/W}$
	Junction And Case	5							$^\circ\text{C/W}$
Typical Junction capacitance (Note 1)	$C_J$	22							pF
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

NOTE: 1.Measured at 1MHz and applied reverse voltage of 4.0 Volts.  
2 Device mounted on 30mm x 30mm x 1mm Cu plate heatsink

FIG.1-MAXIMUM FORWARD SURGE CURRENT

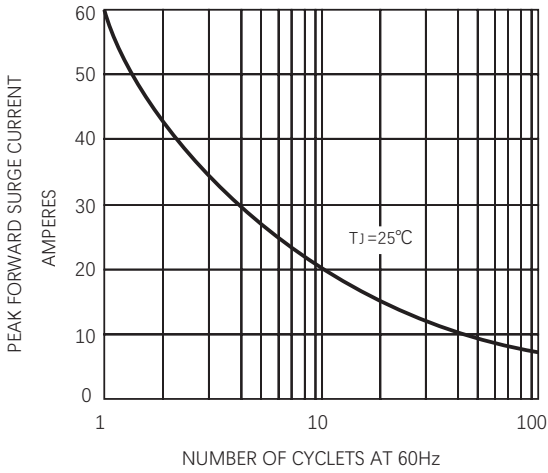


FIG.2 FORWARD CURRENT DERATING CURVE

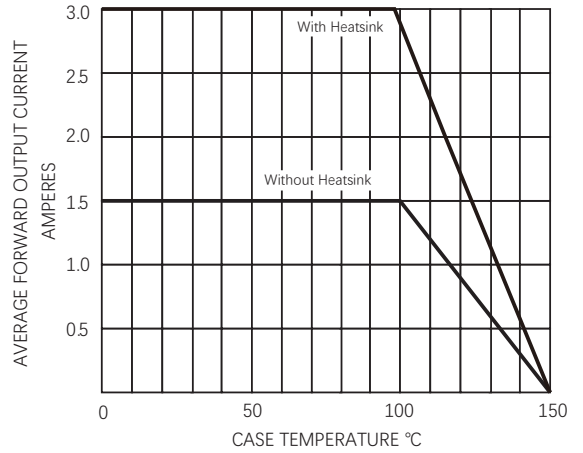


FIG. 3-TYPICAL FORWARD CHARACTERISTICS

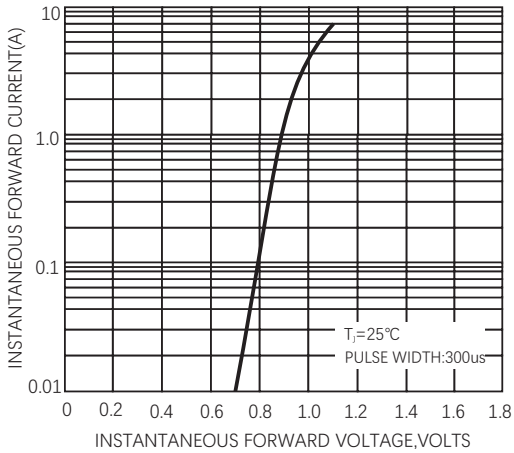
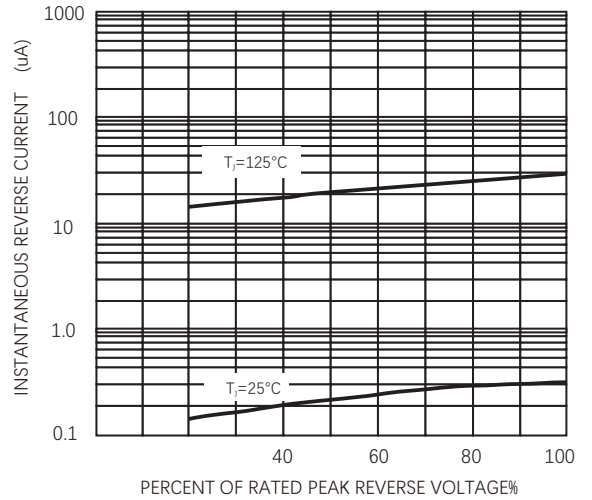


FIG.4 -TYPICAL REVERSE CHARACTERISTICS



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